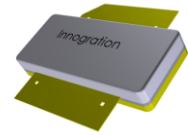


**2500MHz-2700MHz, 150W, 28V High Power RF LDMOS FETs****Description**

The ITCH27150C2 is a 150-watt, internally matched LDMOS FET, designed for multicarrier WCDMA/PCS/DCS/LTE base station and ISM applications with frequencies from 2500 to 2700 MHz. It Can be used in Class AB/B and Class C for all typical cellular base station modulation formats.

ITCH27150C2

•Typical Performance (On Innegration fixture with device soldered):

VDD = 28 Volts, I_{BQ} = 1000 mA, Pulse CW, Pulse Width=100 us, Duty cycle=10% .

Freq	P1dB	P1dB	P1dB Eff	P1dB Gain	P3dB	P3dB	P3dB Eff
(MHz)	(dBm)	(W)	%	dB	(dBm)	(W)	%
2500	51.70	148.10	51.20	13.35	52.55	179.90	52.10
2600	52.18	165.40	52.20	13.06	53.02	200.60	53.70
2700	51.78	150.80	51.90	12.55	52.56	180.20	53.50

ACPR @43dBm_1C-WCDMA

Freq (MHz)	ACPR (dBc)	Gain (dB)	Efficiency (%)
2500	-40.80	14.90	20.00
2600	-42.90	14.50	19.10
2700	-41.30	14.00	19.30

Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Internally Matched for Ease of Use
- Excellent thermal stability, low HCI drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain--Source Voltage	V _{DS}	70	Vdc
Gate--Source Voltage	V _{GS}	-10 to +10	Vdc
Operating Voltage	V _{DD}	+32	Vdc
Storage Temperature Range	T _{stg}	-65 to +150	°C
Case Operating Temperature	T _c	+150	°C
Operating Junction Temperature	T _J	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case T _C = 85°C, T _J =200°C, DC test	R _{θJC}	0.3	°C/W



Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22--A114)	Class 2

Table 4. Electrical Characteristics (TA = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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DC Characteristics

Drain-Source Breakdown Voltage (V _{GS} =0V; I _D =1mA)	V _{DSS}	65	70		V
Zero Gate Voltage Drain Leakage Current (V _{DS} = 28 V, V _{GS} = 0 V)	I _{DSS}			10	μA
Gate--Source Leakage Current (V _{GS} = 10 V, V _{DS} = 0 V)	I _{GSS}			1	μA
Gate Threshold Voltage (V _{DS} = 28V, I _D = 600 uA)	V _{GS(th)}		1.8		V
Gate Quiescent Voltage (V _{DD} = 28 V, I _{DQ} = 1000 mA, Measured in Functional Test)	V _{GS(Q)}	2.3	2.8	3.3	V

Functional Tests (On Innegration demo, 50 ohm system) :V_{DD} = 28 Vdc, I_{DQ} = 1000 mA, f = 2700 MHz, Pulse CW, Pulse Width=20 us, Duty cycle=10% .

Power Gain (Maximum Gain)	G _p		14.8		dB
1 dB Compression Point	P _{-1dB}		51.6		dBm
3dB Compression Point	P _{-3dB}		52.3		dBm
Drain Efficiency@P3dB	η _D		50.1		%
Input Return Loss	IRL		-7		dB

Load Mismatch (On Innegration Test Fixture, 50 ohm system): V_{DD} = 28 Vdc, I_{DQ} = 1000 mA, f = 2700 MHz

VSWR 10:1 at 150W pulse CW Output Power	No Device Degradation
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Reference Circuit of Test Fixture Assembly Diagram

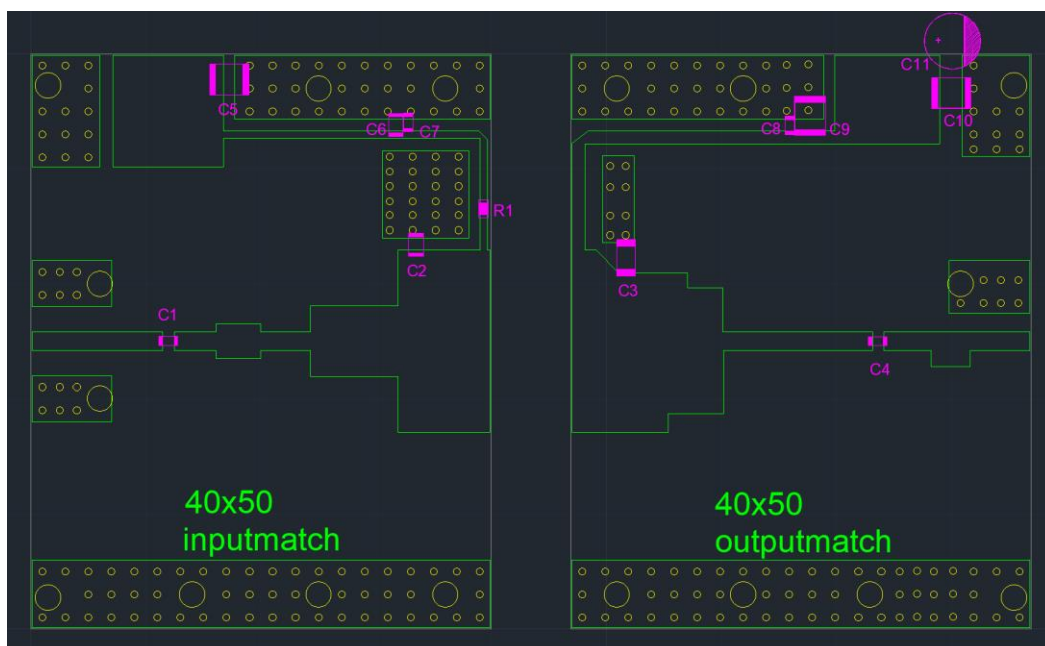


Figure 1. Test Circuit Component Layout

Table 1. Test Circuit Component Designations and Values

Reference	Footprint	Value	Quantity
C1	0603	3.3pF	1
C2	0805	0.8pF	1
C3	0805/1206	0.8pF	1
C4,C7,C8	0603	8.2pF	3
C6	0806	10uF	1
R1	0603	10ohm	1
C5,C9,C10	1210	10uF/63V	3
C11	\	470uF/63V	1
U1	C2	ITCH27150C2	1

TYPICAL CHARACTERISTICS

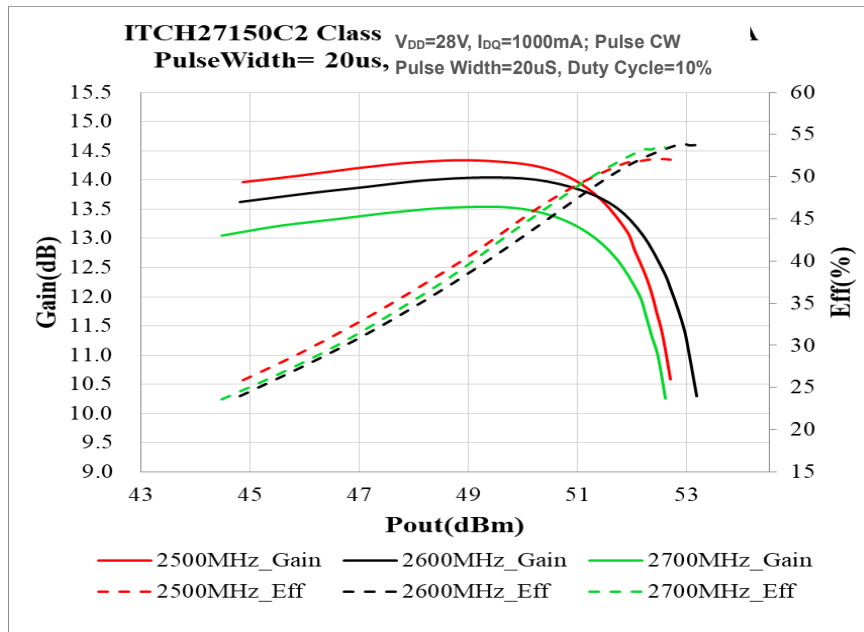


Figure 2. Power gain and drain efficiency as function of
Pulse output power (2500MHz-2700MHz)

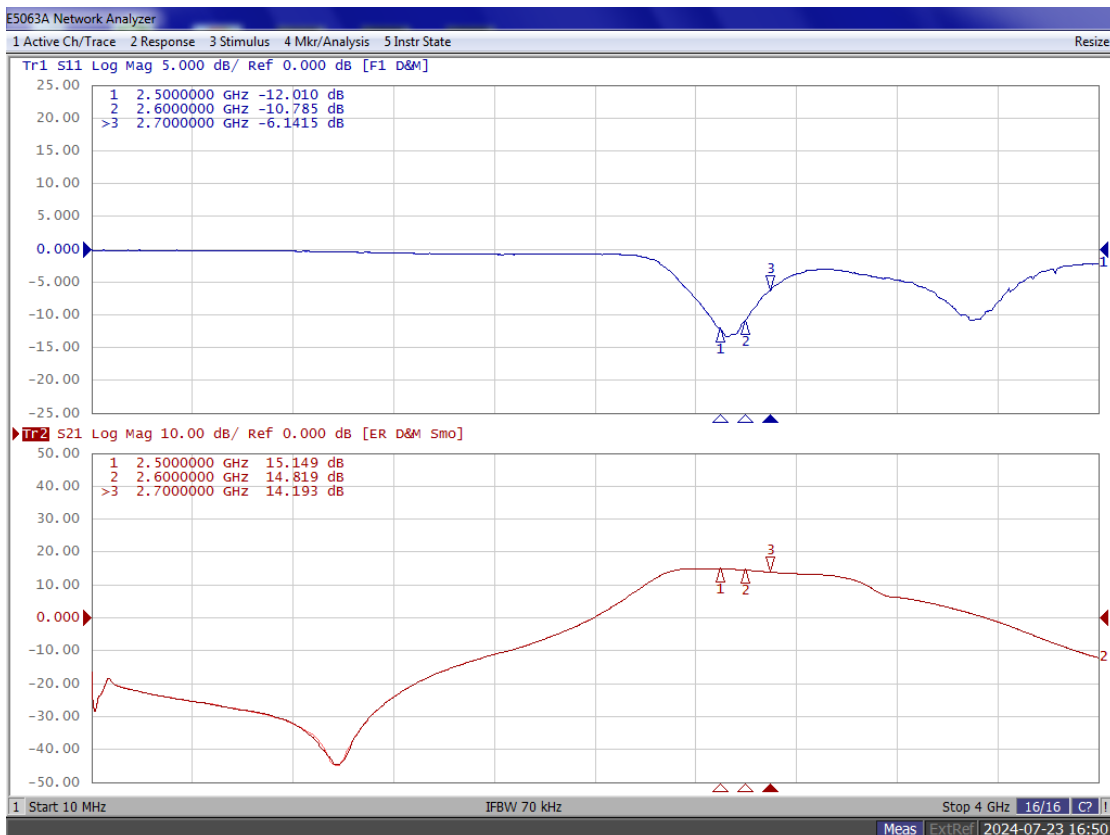


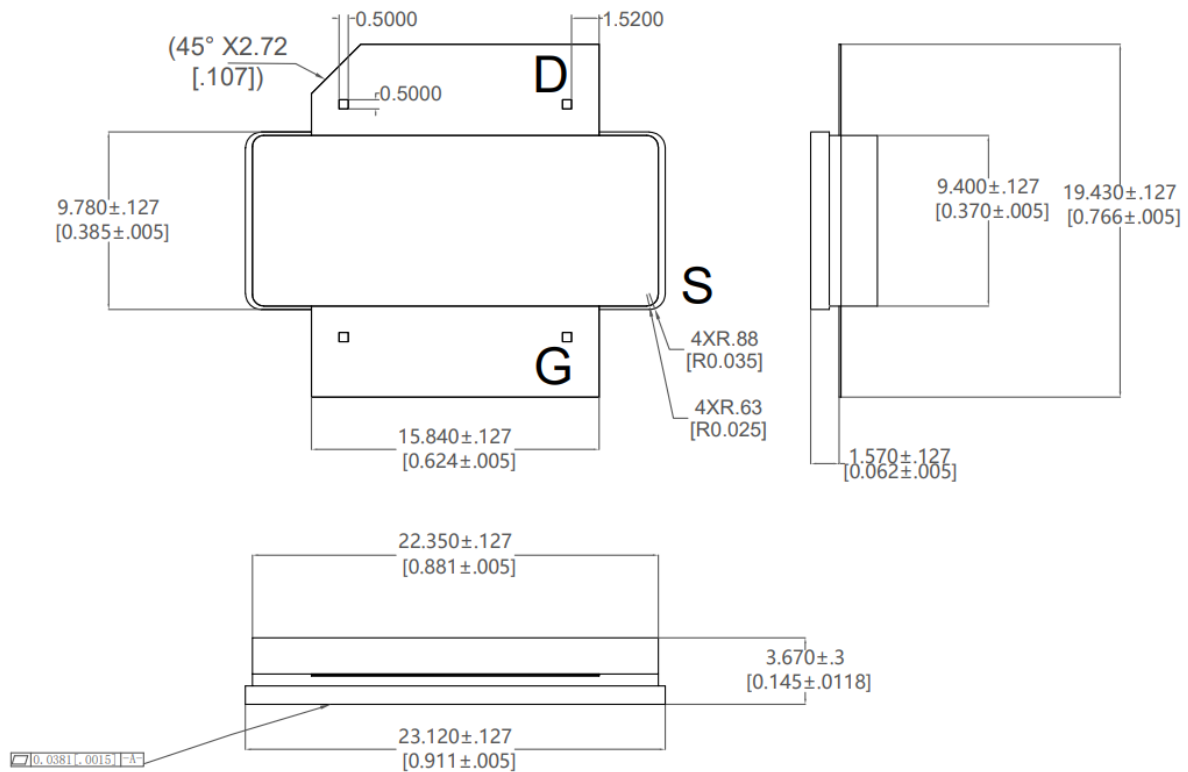
Figure 3. Network analyzer output S11/S21



Package Outline

Flangeless ceramic package;

INP-688-2-EL (C2)



OUTLINE VERSION	REFERENCE			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
PKG-C2					09/27/2018



Revision history

Table 6. Document revision history

Date	Revision	Datasheet Status
2018/12/04	Rev 1.0	Preliminary Datasheet
2024/7/24	Rev 2.0	Change application data according to new tuning

Application data based on CWZ-24-17

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